



1-2 December 2020

Thai Nguyen University of Technology
Thai Nguyen, Vietnam

CALL FOR PAPERS

icera@tnut.edu.vn

<http://icera2020.tnut.edu.vn/>

We are pleased to invite you to submit the original paper(s) for “International Conference on Engineering Research and Applications (ICERA 2020)”.

This conference aims to provide an international forum to disseminate information on the most recent and relevant researches, theories, and practices in engineering research and applications. The conference is dedicated to the 55th anniversary of Thai Nguyen University of Technology. All submissions are subjected to rigorous review before an acceptance decision is made. This conference will be attended by participants from USA, Canada, Australia, Germany, Korea, Taiwan, China, Philippines, Indonesia, Vietnam and other countries.

ORGANIZED BY



TECHNISCHE UNIVERSITÄT
ILMENAU

PUBLISHED BY



Springer

INDEXED IN SCOPUS

IN PARTNERSHIP WITH



ORGANIZING COMMITTEE

Honorary Co-Chairs

Banh Tien Long, VASE, Vietnam
Nguyen Huu Cong, Vice President, TNUT, Vietnam
Prof. Dr.-Ing. habil. Kai-Uwe Sattler, Vice President, Technische Universität Ilmenau, Germany

General Co-Chairs

Nguyen Duy Cuong, Rector, TNUT, Vietnam
Vu Ngoc Pi, Vice Rector, TNUT, Vietnam

Program Co-chairs

Pham Thanh Long, TNUT, Vietnam
Horst Puta, Ilmenau, Germany

Organizing Co-chairs

Dao Huy Du, TNUT, Vietnam
Vu Duc Thai, ICTU, Vietnam
Nguyen Thi Thanh Ha, TNUT, Vietnam
Do Thi Tam, TNUT, Vietnam

Keynote Speakers

Prof. Dr.-Ing. habil. Kai-Uwe Sattler, TU Ilmenau, Germany
Prof. Dr. Banh Tien Long, VASE, Vietnam
Prof. Dr. Roger A. Sauer, RWTH Aachen University, Germany
Prof. Dr. Pierre-Yves Jouan, Nantes University, Nantes, France
Prof. Dr. Chen-Fu Chien, National Tsing Hua University, Taiwan
Prof. Dr. Trung Q. Duong, Queen's University Belfast, UK
Prof. Dr. Kung-Hwa Wei, National Chiao Tung University, Taiwan

IMPORTANT DATES

Submission deadline: **31 July 2020**
Notification date: **15 September 2020**
Registration deadline: **10 October 2020**

SUBMISSION

Authors are requested to prepare papers in line with **Springer-template**. Paper submission should not exceed 6 pages and must be submitted through the conference's page

<https://easychair.org/conferences/?conf=icera2020>

TOPICS

Mechanical Engineering Track

Machining Processes
Non-traditional Machining Processes
Advanced Manufacturing and Automation
Dynamics, Vibration and Control
Metrology and Machine Tool Modeling
CAD/CAM
Machine and Machinery Design
Computational Heat and Mass Transfer

Materials and Mechanics of Materials Track

Applied Surfaced Engineering
Materials Manufacturing and Processing
Mechanical Behavior of Materials
Mechanics of Composites
Engineering Materials and Applications
Mechanics of Advanced Materials
Applied Mechanics

Mechatronics and Micro Mechatronics Track

Micro/nano fabrication and manufacturing technologies
Mechatronics Applications
Sensors and Actuators
Micromechanics and Nanomechanics
Microrobotics, micro/nano systems and micromechatronic systems integration
Silicon and other advanced materials for MEMS and NEMS
Robotics Systems
Precision Metalworking Technology

Automotive Engineering Track

Electric and Hybrid Vehicles
Automotive Engines
Automotive Dynamics
Vibration, Noise and Harshness

Electrical and Electronics Engineering Track

Digital Signal Processing and Applications
Power Electronics and Systems
Automation, Robotics and Control
Electrical Measurements
Communication and Electronics Engineering
IC Technologies
Modeling and Simulations
Devices, Circuits and Systems
Energy Systems
Intelligent Transportation Systems
Wireless systems
Networked Control Systems
Fuzzy and Neural Control
Process Control Systems

Information and Communication Technology Track

Information Systems
Software Engineering
Computer Network and Security
Internet of things and Smart Cities
Embedded Systems
Natural Language Processing
Intelligence Systems
Parallel and Distributing Computing
Grid and High-Performance Computing
Information and Coding Theory
Data Mining and Big Data
Telecommunications Systems
Artificial Intelligence